TECHNOPARTNER

S720AB

Silicone Potting Compound

REACH Compliant RoHS Compliant

Features

- Good thermal conductivity
- Room temperature
- High stability
- Water proof

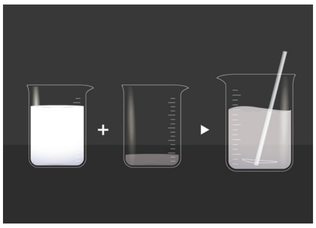
Applications

Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED, Mother Board,Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless Hub, DDR ll Module, etc.

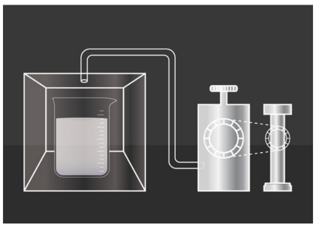
Storage

Epoxy Potting Compound has a shelf-life of twelve (12) months from the date of manufacture, as indicated by the lot number, when stored in the original, unopened contained at or below 25° C.

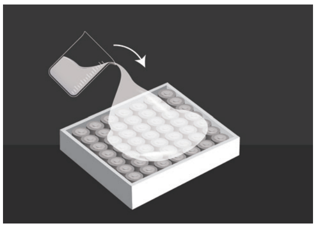
Operation Manual



① Mix component A and B.



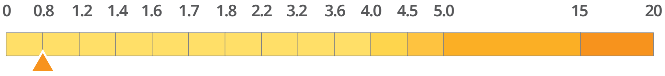
② Vacuum out air.



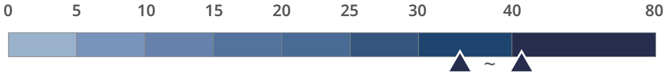
③ Pour potting compound.

Properties

Thermal Conductivity : 0.8 W/mK



Hardness : 34~43 (Shore A)



Properties	S720AB	Unit	Tolerance	Test Method
Thermal Conductivity	0.8	W/mK	±10%	ASTM D5470
Color	White	-	-	Visual
Dielectric Breakdown Voltage	6.1	KV/mm	±10%	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Density	1.97	g/cm^3	±10%	ASTM D792
Working Temperature	-40~+180	° C	-	-
Viscosity	2000~3000	cps	-	ASTM D2393
Curing Time @25° C	35	Hrs	-	-
Standard Format	1kg	Pot	-	-
Hardness	34~43	Shore A	±4~5	ASTM D2240
Mixing Ratio	100:2	gram	-	-

▶ Component A is a mixed material of epoxy and thermal conductive powder. It is normal to cause precipitation and stratification due to different density. Before use, please use a flat spatula or other stainless tools to evenly mix component A to achieve the best thermal conductivity.